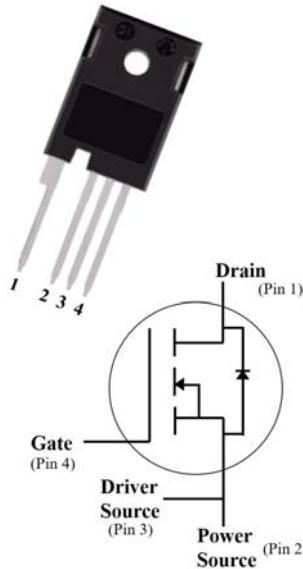


Silicon Carbide Power MOSFET (N-Channel Enhancement)

V_{DS}	1200V
$I_D(25^\circ\text{C})$	39A
$R_{DS(on)}$	80mΩ



Features

- High speed switching
- Essentially no switching losses
- Reduction of heat sink requirements
- Maximum working temperature at 175 °C
- High blocking voltage
- Fast Intrinsic diode with low recovery current
- High-frequency operation
- Halogen free, RoHS compliant
- AEC-Q101 qualified

Typical Applications

Typical applications are in power factor correction(PFC), solar inverter, uninterruptible power supply, motor drives, photovoltaic inverter, electric car and charger.

Mechanical Data

- **Package:** TO247-4L
- **Terminals:** Tin plated leads
- **Polarity:** As marked

■ Maximum Ratings ($T_c=25^\circ\text{C}$ Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE	TEST CONDITIONS	NOTE
Device marking code				D212080NCFG1Q	
Drain source voltage @ $T_j=25^\circ\text{C}$	$V_{DS,max}$	V	1200	$V_{GS}=0\text{ V}$, $I_D=100\mu\text{A}$	
Gate source voltage @ $T_j=25^\circ\text{C}$	$V_{GS,max}$	V	-8/+22	Absolute maximum values	Note1
Gate source voltage @ $T_j=25^\circ\text{C}$	$V_{GS,op}$	V	-4/+18	Recommended operational values	Note2
Continuous drain current @ $T_c=25^\circ\text{C}$	I_D	A	39	$V_{GS}=18\text{V}$, $T_c=25^\circ\text{C}$	Fig.18
Continuous drain current @ $T_c=100^\circ\text{C}$			28	$V_{GS}=18\text{V}$, $T_c=100^\circ\text{C}$	
Pulsed drain current	$I_{D(pulsed)}$	A	80	Pulse width t_p limited by $T_{j,max}$	Fig.23
Power Dissipation	P_{TOT}	W	223	$T_c=25^\circ\text{C}$, $T_j = 175^\circ\text{C}$	Fig.17
Power Dissipation			97	$T_c=110^\circ\text{C}$, $T_j = 175^\circ\text{C}$	
Operating junction and Storage temperature range	T_j, T_{stg}	°C	-55 to +175		
Soldering temperature	T_L	°C	260	1.6mm (0.063") from case for 10s	
Mounting torque	T_M	Nm	0.6	M3 screw Maximum of mounting process: 3	



YJD212080NCFG1Q

■ Static Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Gate threshold voltage	V _{GS(th)}	V	2.3	2.9	3.6	V _{DS} =V _{GS} , I _D =5mA	Fig.4, 11
				2.2		V _{DS} =V _{GS} , I _D =5mA, Tj=175°C	
Drain source breakdown voltage	V _{(BR)DSS}	V	1200			V _{GS} =0, I _D =100uA	
Zero gate voltage drain current	I _{DSS}	uA		1	10	V _{DS} =1200V, V _{GS} =0V	Fig.16
Gate source leakage current	I _{GSS}	nA			100	V _{GS} =18V, V _{DS} =0V	
Current drain source on-state resistance	R _{DS ON}	mΩ		77	85	V _{GS} =18V, I _D =20A	Fig.5, 6, 7
				122		V _{GS} =18V, I _D =20A, Tj=175°C	
Internal gate resistance	R _g	Ω		3.1		f=1MHz	
Diode forward voltage	V _{SD}	V		3.9		V _{GS} =-4V, I _{SD} =10A	Fig.8
				3.2		V _{GS} =0V, I _{SD} =10A Tj=175°C	Fig.9
Transconductance	g _f	S		10		V _{DS} =16V, I _D =20A	Fig.4
				9.2		V _{DS} =16V, I _D =20A, Tj=175°C	

■ Dynamic Electrical Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Input capacitance	C _{iss}	pF		890		V _{DS} =1000V, V _{GS} =0V, Tj=25°C, f=1MHz, V _{AC} = 25mV	Fig.13, 14
Output capacitance	C _{oss}			58			
Reverse capacitance	C _{rss}			4			
C _{oss} stored energy	E _{oss}	uJ		34			Fig.15
Gate source charge	Q _{gs}	nC		12		V _{DS} =800V, V _{GS} =-4/18V, I _D =20A	Fig.12
Gate drain charge	Q _{gd}			11			
Gate charge	Q _g			41			

■ Switching Characteristics (Tc=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Turn on switching energy	E _{on}	uJ		377		V _{DD} =800V, V _{GS} =-4/+15V, I _D =20A, R _g =0Ω, L=16.7uH	Fig.21, 22
Turn off switching energy	E _{off}			14			
Turn on delay time	t _{d(on)}	ns		21			Fig.21, 22
Rise time	t _r			17			
Turn off delay time	t _{d(off)}	ns		14		V _{DD} =800V, V _{GS} =-4/+15V, I _D =20A, R _g =0Ω, L=16.7uH	Fig.21, 22
Fall time	t _f			8			



■ **Body diode characteristics** (T_c=25°C unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Min.	Typ.	Max.	Test Conditions	Note
Diode forward voltage	V _{SD}	V		3.9		V _{GS} =-4V, I _{SD} =10A	Fig.8
				3.2		V _{GS} =0V, I _{SD} =10A, T _j =175°C	Fig.9
Continuous diode forward current	I _S	A		39		T _c =25°C	Note1
Reverse recovery time	trr	nS		28.24		V _R =800V, V _{GS} =-4V, I _D =20A, di/dt=2095A/uS	
Reverse recovery charge	Qrr	nC		190			
Peak reverse recovery current	Irrm	A		30.08			

Note 1: When using SiC Body Diode the maximum recommended V_{GS} = -4V

Note 2: MOSFET can also safely operate at 0/18 V

■ **Thermal Characteristics** (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Value
Thermal resistance	R _{θJ-C}	°C /W	0.67

■ **Typical Characteristics**

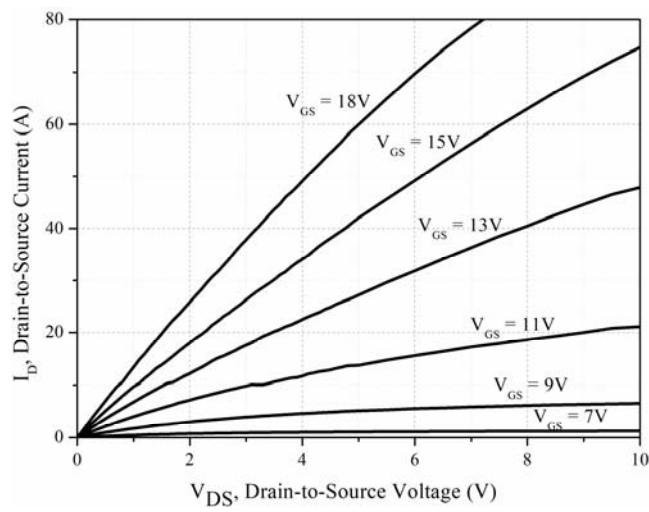


Figure 1. Output Characteristics T_j = -40°C

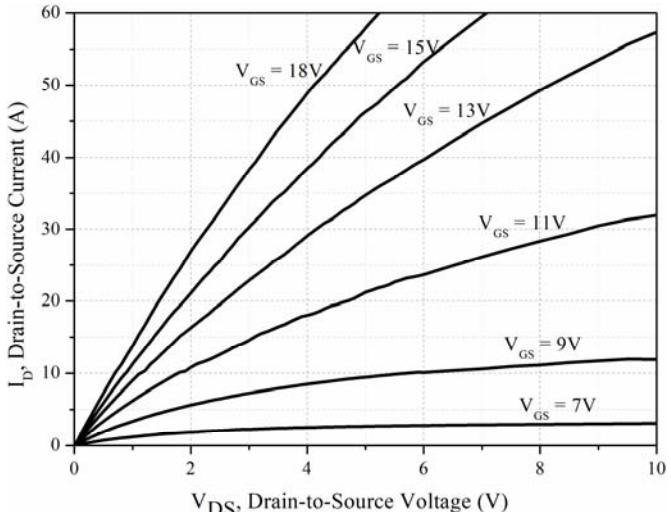


Figure2. Output Characteristics T_j = 25°C

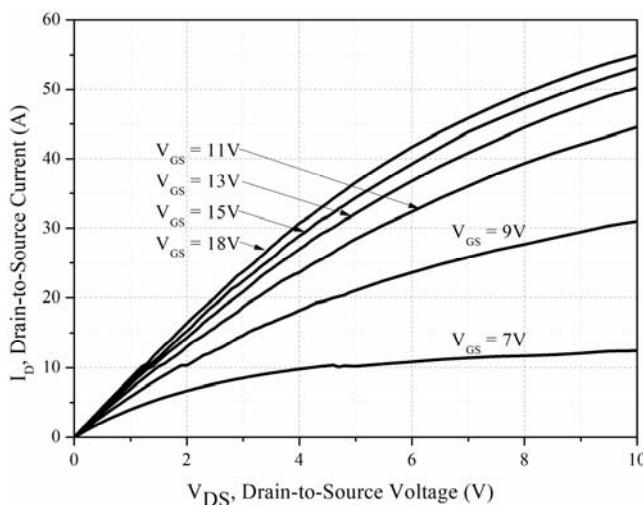


Figure 3. Output Characteristics $T_j = 175^\circ\text{C}$

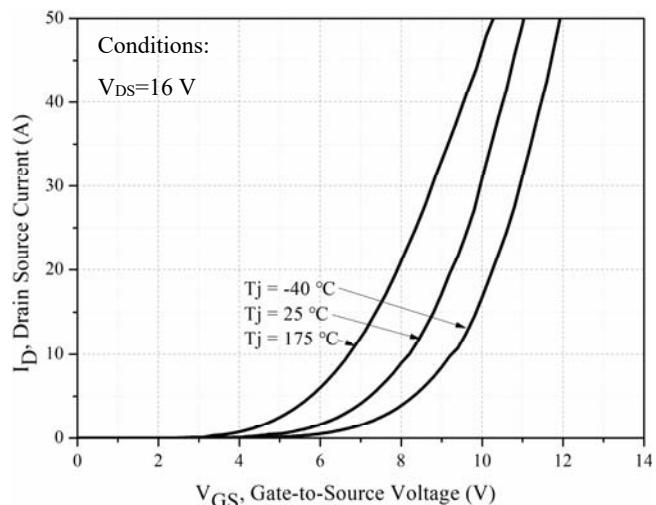


Figure 4. Transfer Characteristics for various junction temperature

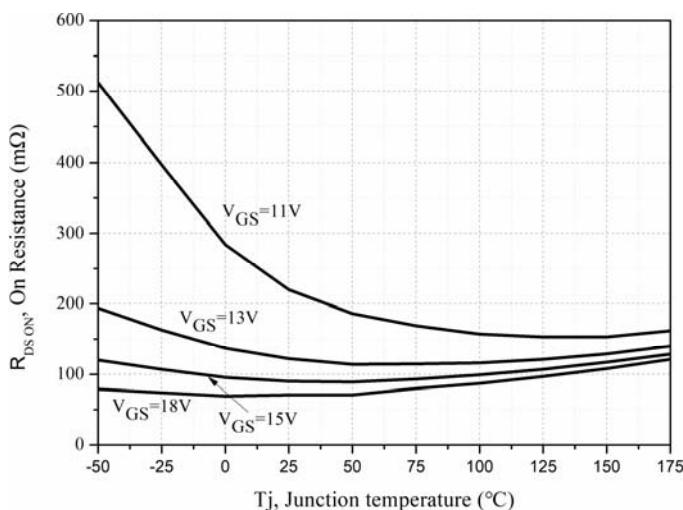


Figure 5. On-resistance vs. temperature for various gate voltage

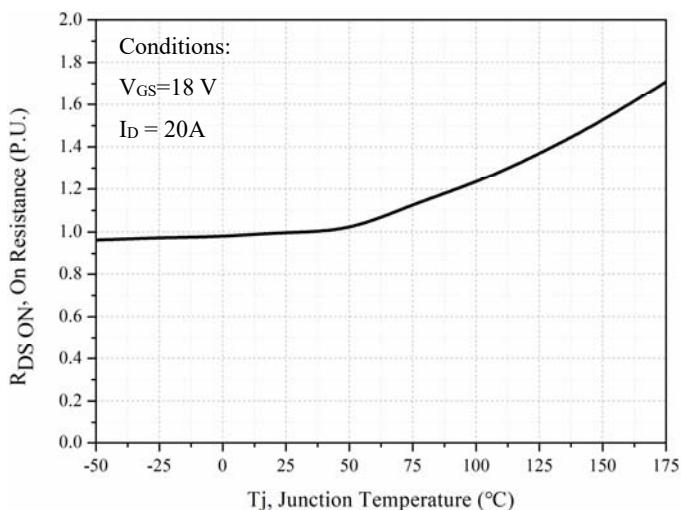


Figure 6. Normalized on-resistance vs. temperature

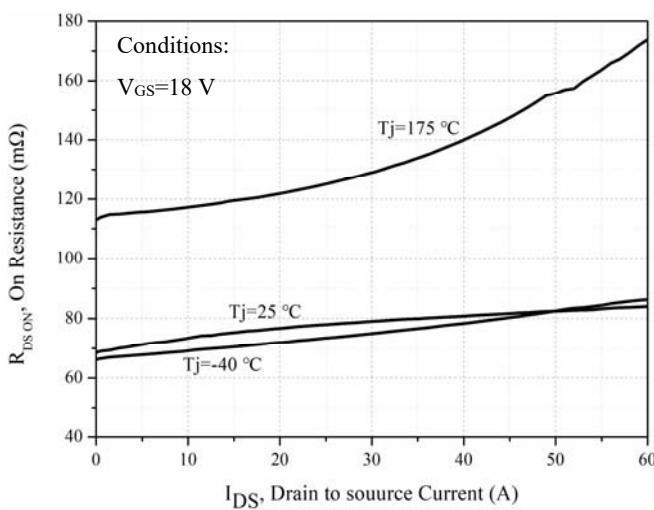


Figure 7. On-resistance vs. drain current

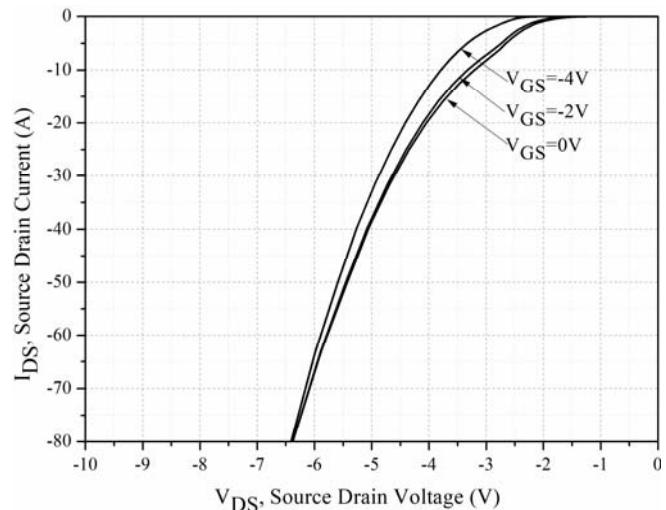


Figure 8. Body diode characteristic at $T_j = 25^\circ\text{C}$



YJD212080NCFG1Q

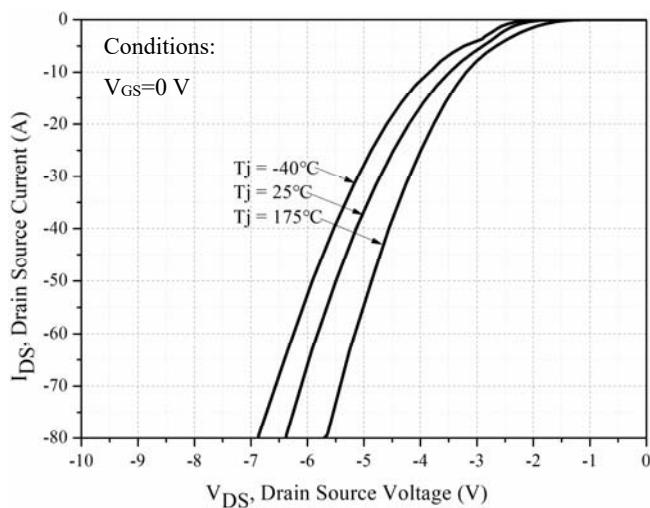


Figure 9. Body diode characteristic

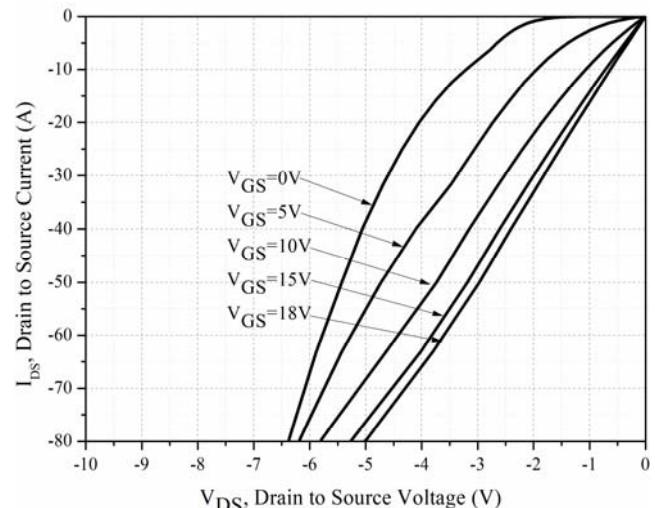


Figure 10. 3rd quadrant characteristic at $T_j = 25^\circ\text{ C}$

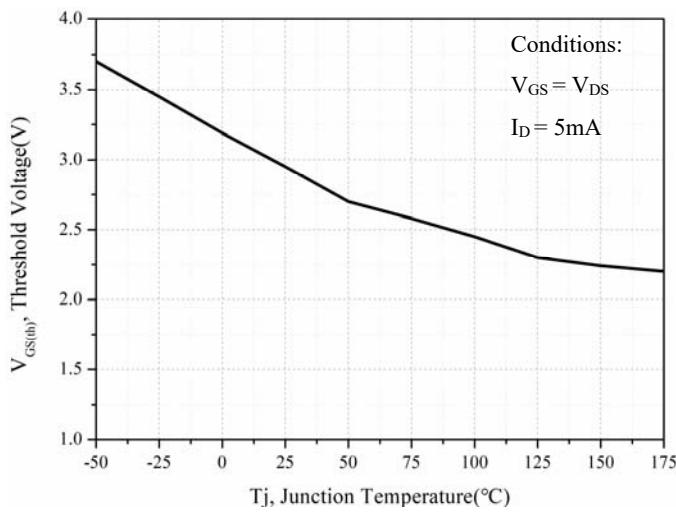


Figure 11. Threshold voltage vs. temperature

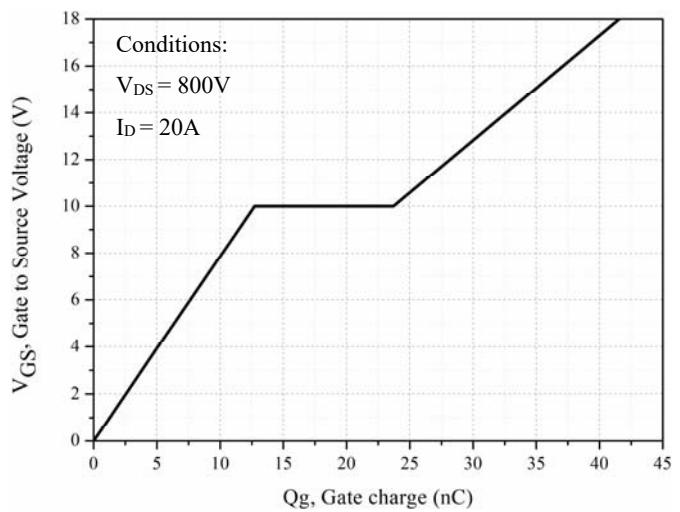


Figure 12. Gate charge characteristic

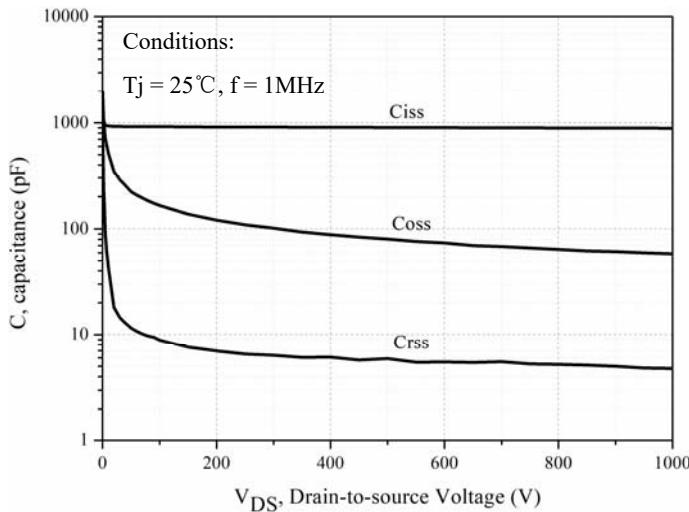


Figure 13. Capacitances vs. drain source voltage (0-1000V)

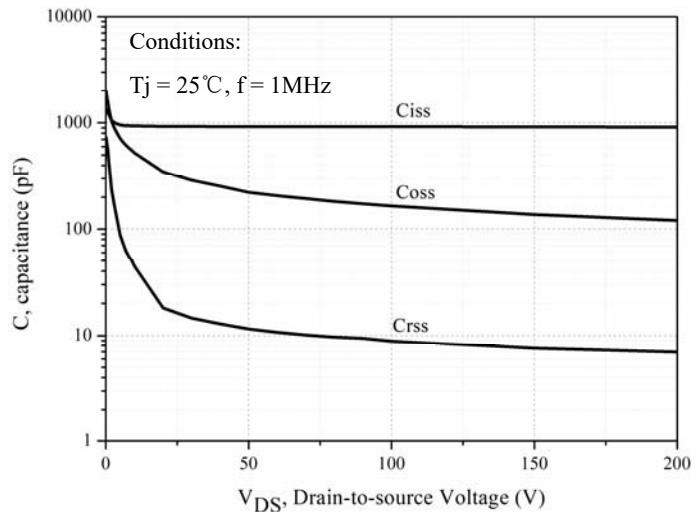
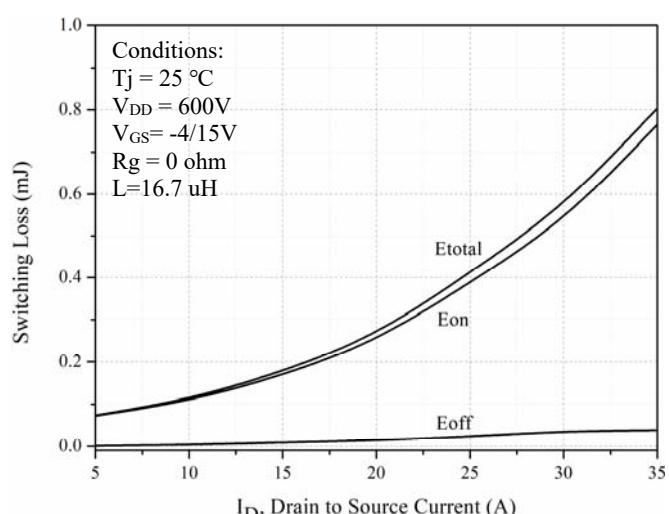
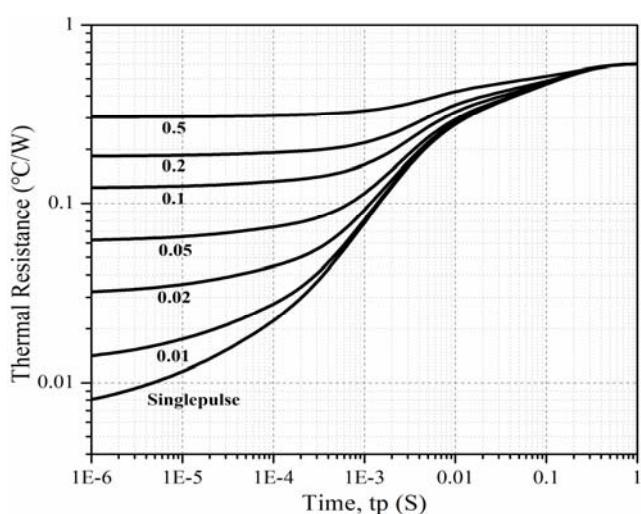
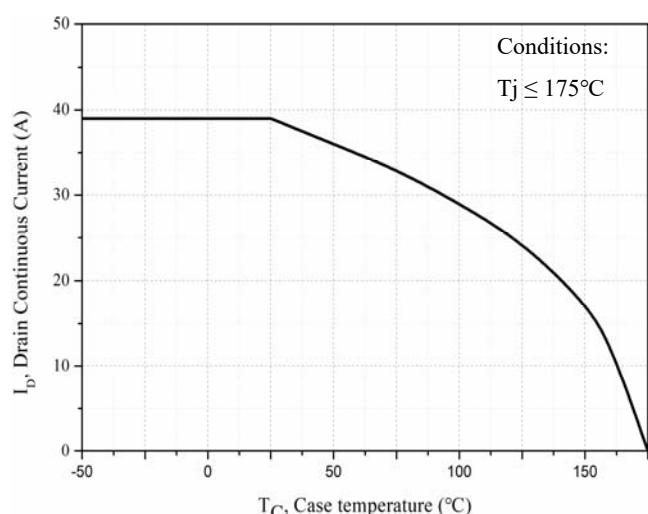
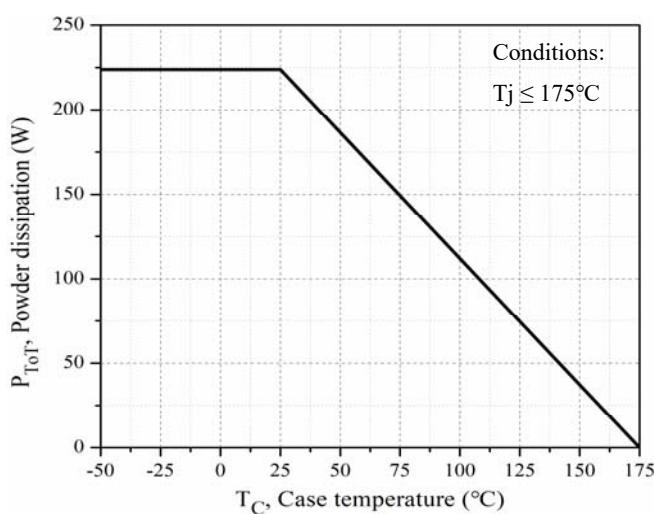
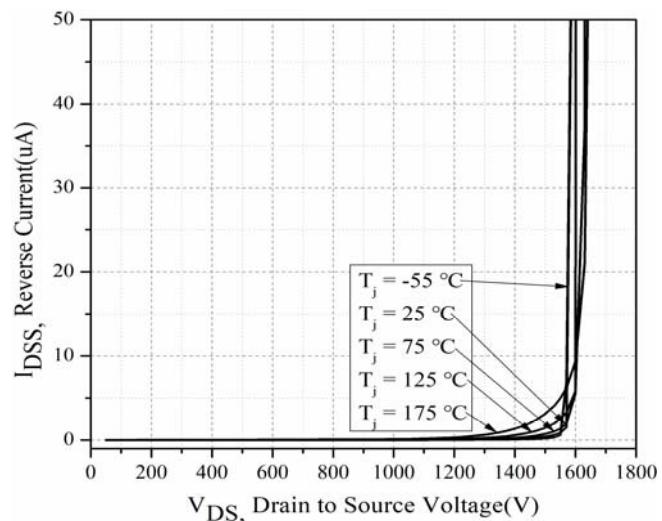
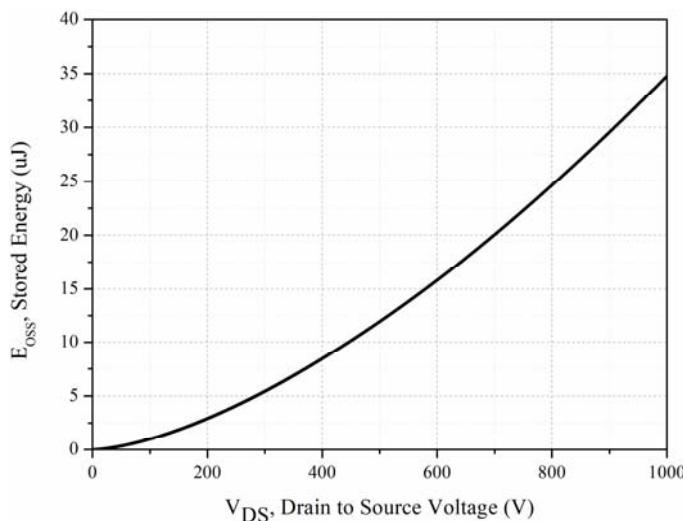


Figure 14. Capacitances vs. drain source voltage (0-200V)



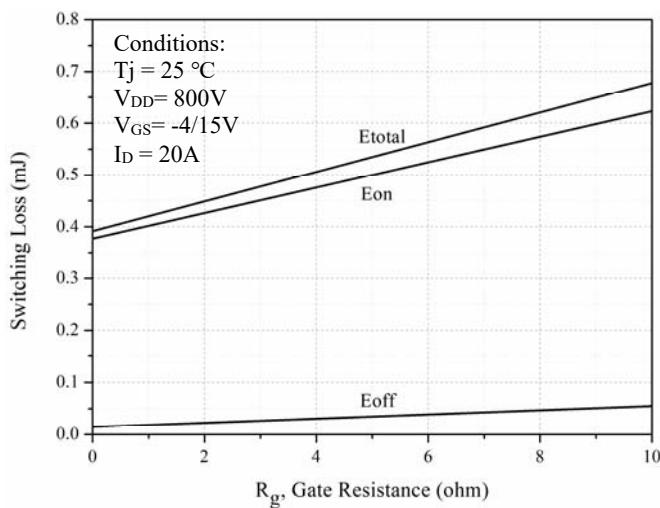


Figure 21. Clamped inductive switching energy vs. R_g

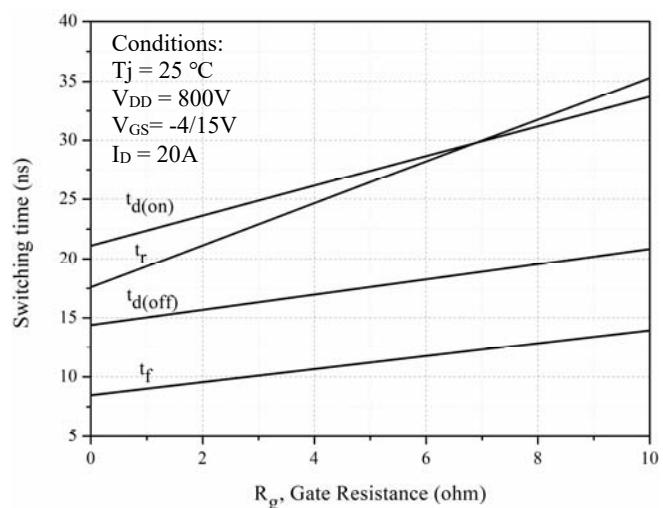


Figure 22. Switching times vs. R_g

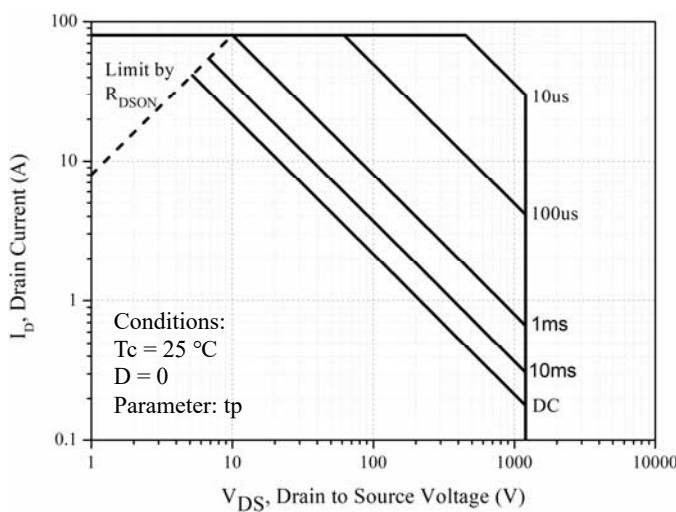


Figure 23. Safe operating area

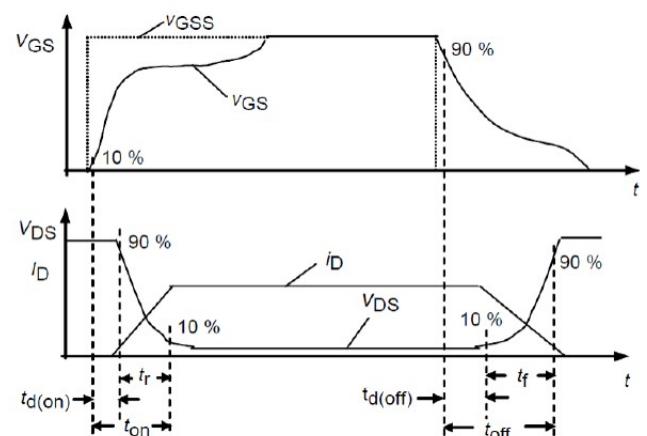


Figure 24. Switching Times Definition

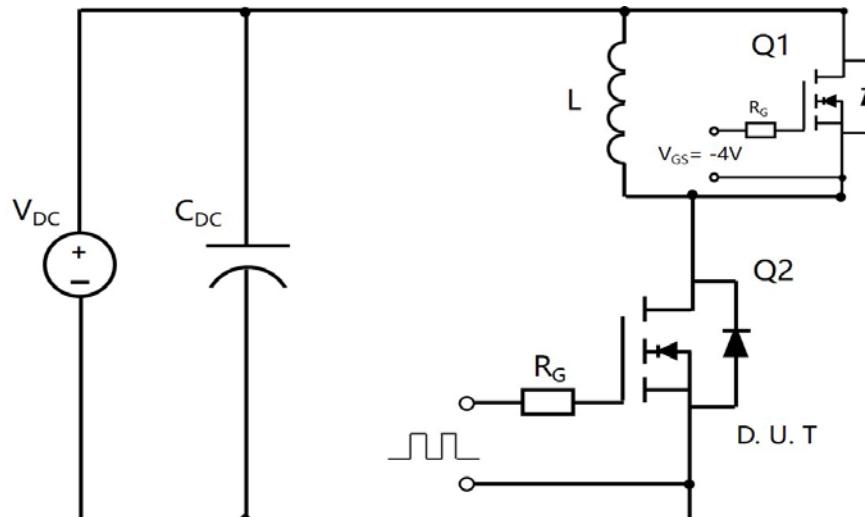
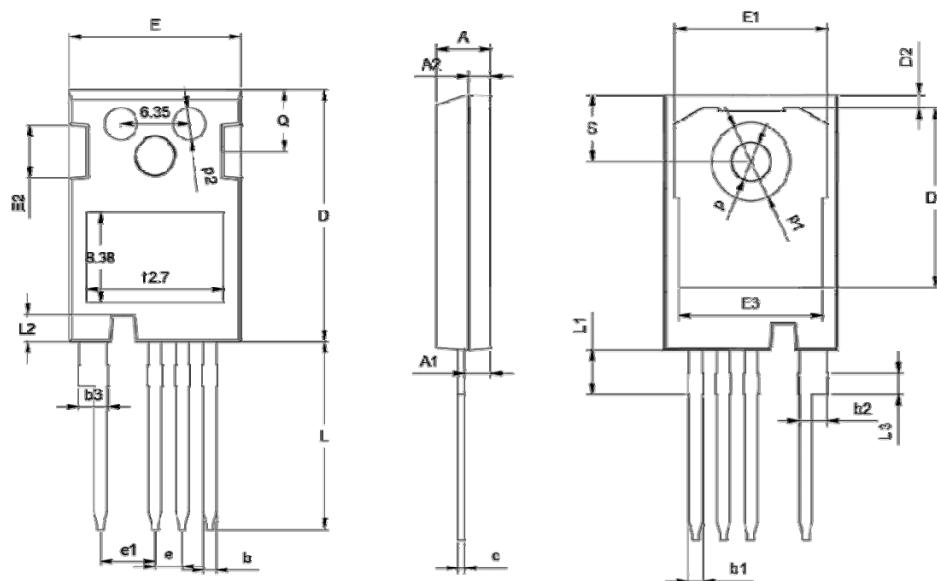


Figure 25. Clamped Inductive Switching Waveform Test Circuit



■Outline Dimensions



TO247-4L			
Dim	Min	Norm	Max
A	4.80	5.00	5.20
A1	2.30	2.40	2.50
A2	1.88	1.98	2.08
b	1.10	1.20	1.30
b1	1.20	/	1.50
b2	2.35	2.55	2.75
b3	2.45	/	2.85
c	0.55	0.60	0.65
D	23.3	23.45	23.6
D1	16.25	16.55	16.85
D2	1.00	/	1.30
e	TYP2.54		
e1	TYP5.06		
E	15.75	15.90	16.05
E1	13.80	/	14.20
E2	4.40	4.75	5.10
E3	13.00	/	13.45
L	17.34	17.49	17.64
L1	4.00	/	4.30
L2	2.35	/	2.65
L3	TYP1.98		
Q	5.60	5.80	6.00
S	6.05	/	6.30
p	TYP3.58		
p1	TYP7.18		
p2	TYP3.00		



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